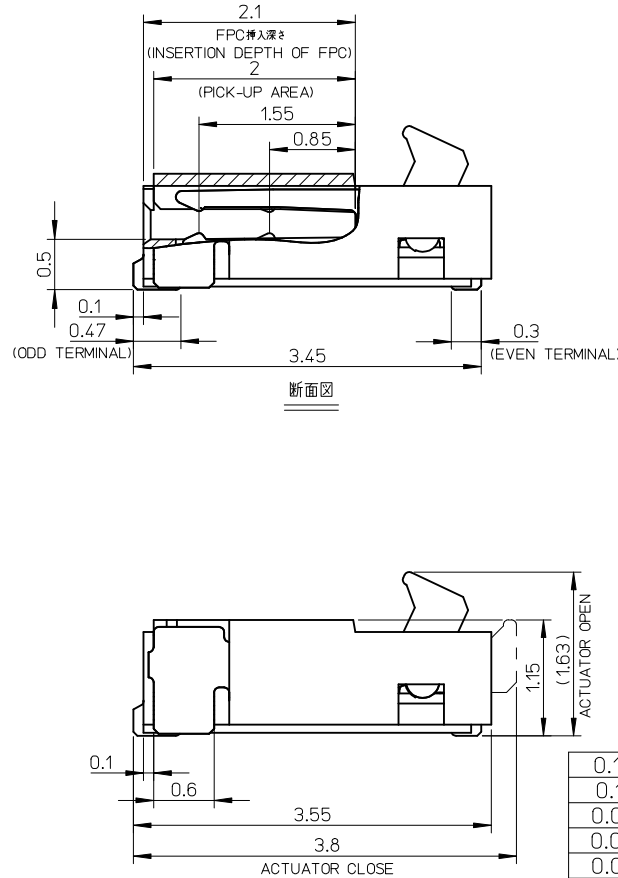
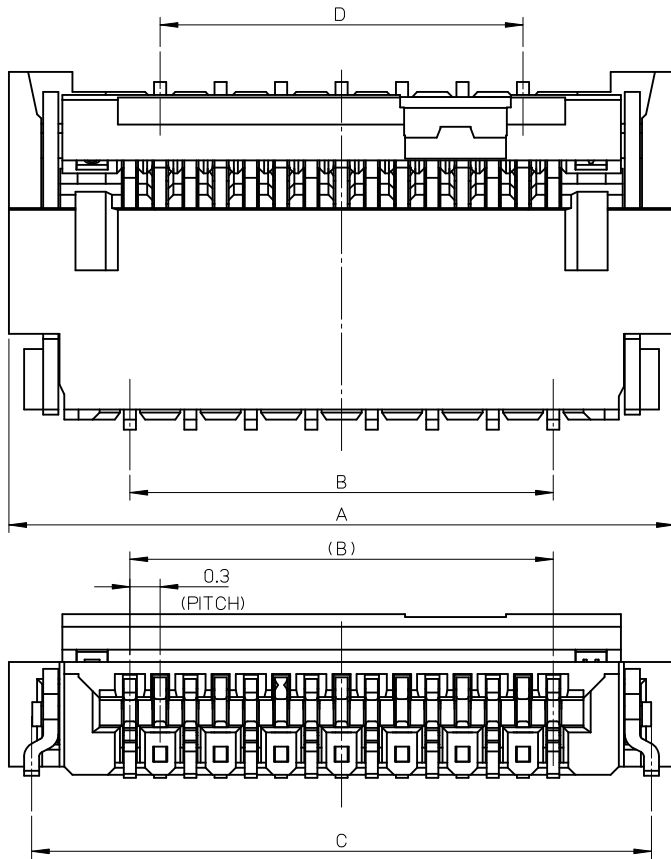




注記 NOTES:

1.材質 MATERIAL

ハウジング: LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER, WHITE (NATURAL)
GLASS FILLED, UL94V-0
アクチュエータ: ポリアミド樹脂
黑色、ガラス充填、UL94V-HB

ACTUATOR: POLYAMIDE

BLACK GLASS FILLED, UL94V-HB

ターミナル: 銅合金 (t=0.12)

TERMINAL: COPPER ALLOY (t=0.12)

金具: 焼青銅 (t=0.15)

NAIL: PHOSPHOR BRONZE (t=0.15)

2.めっき仕様 PLATING

ターミナル TERMINAL

接点部: 金めっき 0.1μm以上

CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM

半田付け部: 金めっき

SOLDER TAIL AREA: GOLD

下地めっき: ニッケル 1.0μm以上

UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

金具 NAIL

銅めっき 1.0μm以上

TIN PLATING 1.0 MICROMETER MINIMUM

下地めっき: ニッケル 1.0μm以上

UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

3.平坦度は、0.1ミリ以下とする。

TAILS COPLANARITY TO BE 0.1 MAXIMUM.

4.製品の取り扱いについては、コネクタ取り扱い説明書 (AS-502598-001) を参照願います。

PLEASE REFER TO INSTRUCTION MANUAL (AS-502598-001)
FOR 0.3 FPC CONNECTOR BACK FLIP.

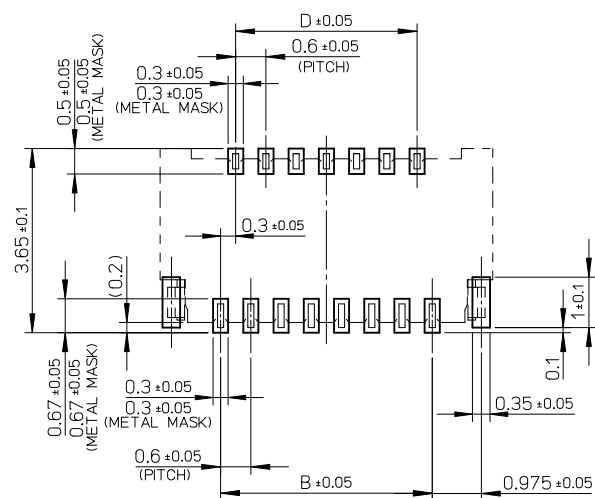
5.ELV及びRoHS適合品

ELV AND RoHS COMPLIANT

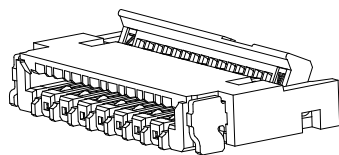
0.125	14.4	16.95	15	17.4	502598-5191	51
0.112	12.6	15.15	13.2	15.6	502598-4591	45
0.098	10.8	13.35	11.4	13.8	502598-3991	39
0.085	9	11.55	9.6	12	502598-3391	33
0.077	7.8	10.35	8.4	10.8	502598-2991	29
0.072	7.2	9.75	7.8	10.2	502598-2791	27
0.068	6.6	9.15	7.2	9.6	502598-2591	25
0.063	6	8.55	6.6	9	502598-2391	23
重さ (g) WEIGHT (g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES NO. 502598-**11

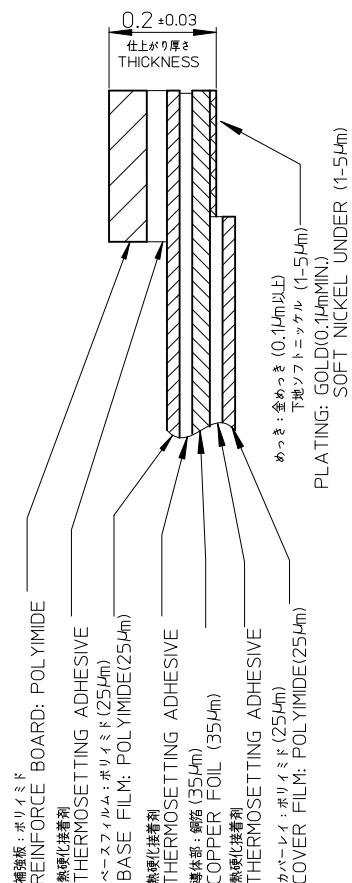
REVISED EC NO. :J2012-0121 DRWN:YUHASEGAWA 2011/07/25 CHKD:K TAKAHASHI 2011/07/25 APPR:KMORIKAWA 2011/07/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY				
		10 OVER 30 UNDER	± 0.25	CHECKED BY HSHIMOYAMA	DATE 2009/07/21					
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2009/07/21	MOLEX INCORPORATED				
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-001		1 OF 2			
	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



推奨基板寸法
RECOMMENDED P.W.B. PATTERN LAYOUT
推奨メタルマスク厚: $t=0.1\text{mm}$
RECOMMENDED METAL MASK THICKNESS: $t=0.1\text{mm}$

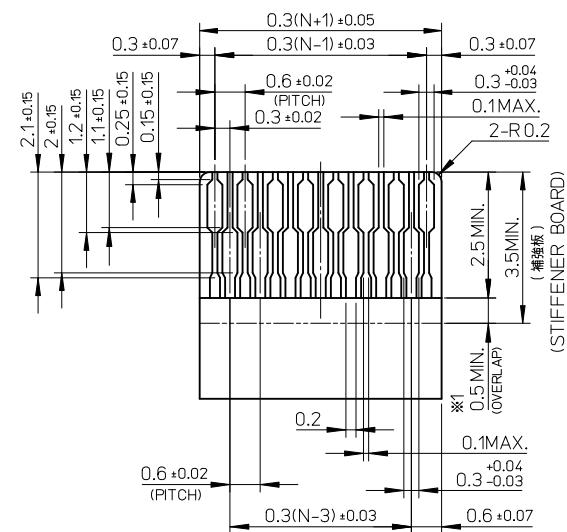


ISO VIEW (参考)



FPC構成推奨仕様

STRUCTURE OF FPC



N: 極数
N:CIRCUITS

適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:

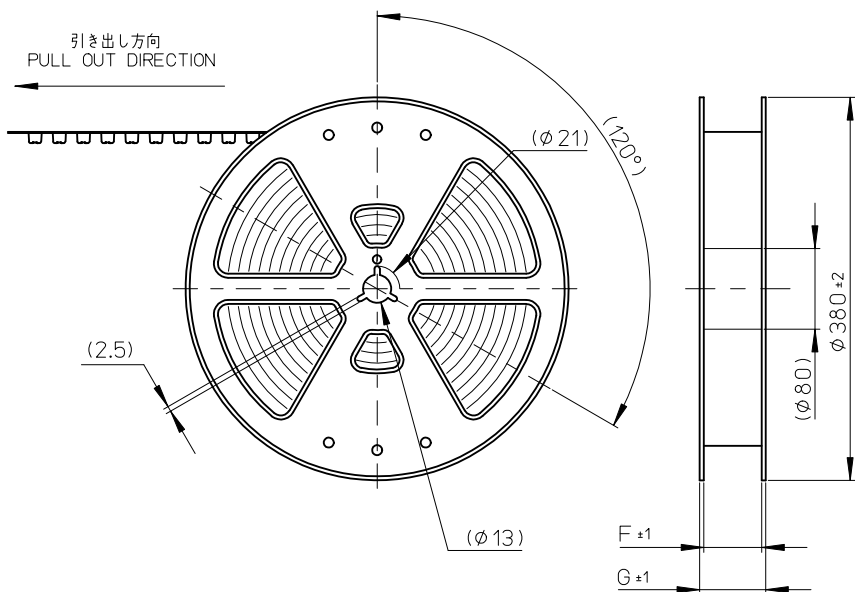
抜き方向は、導体側から補強板側を推奨致します。
 補強フィルム材質は、ポリイミドを推奨致します。
 接着剤は熱硬化性接着剤を推奨致します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、
 染み出しが無い様、お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE
ADHERING BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN
ELECTRICAL CONTINUITY.

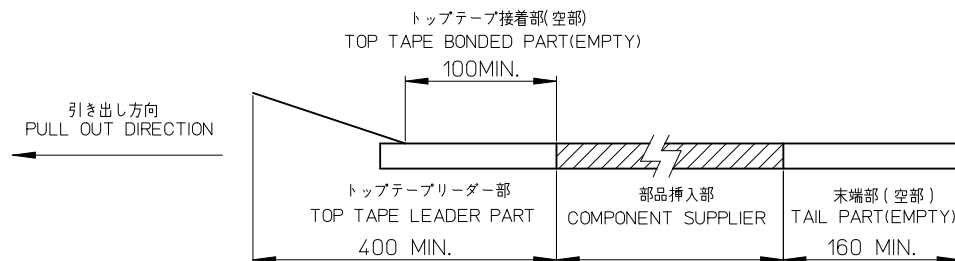
※1 補強板の長さが図面通りに確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください。
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM.

REVISED EC NO: J2012-0121 DRAWN:YUASEGAWA 2011/07/25 CHKD:K TAKAHASHI 2011/07/25 APPR:KMORI KAWA 2011/07/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ++	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY				
		10 OVER 30 UNDER	± 0.25	CHECKED BY HSHIMOYAMA	DATE 2009/07/21					
		30 OVER	± 0.3	APPROVED BY KMORI KAWA	DATE 2009/07/21	MOLEX INCORPORATED DOCUMENT NO. SD-502598-001 SHEET NO. 2 OF 2				
		ANGULAR ±1 °		MATERIAL NO. SEE TABLE						
	REV	C	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



注記)
NOTES

- 製品番号502598-**-11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 502598-**-11 DETAIL DIMENSIONS,
SEE SALES DRAWING FOR CONNECTOR.
- 梱包数量: 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- カバートープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
- 材料
MATERIAL
キャリアテープ: ポリスチレン (PS)
CARRIER TAPE: POLYSTYRENE (PS)
トップテープ: ポリエチレンテレフタレート (PET)、他
TOP TAPE : POLYETHYLENE TELEPHTHALATE (PET), OTHERS
リール: ポリスチレン (PS)
REEL: POLYSTYRENE (PS)
- ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT

REVISED EC NO: J2011-0028 DRWN: HONO01 CHKD: HSHIMOYAMA APPR: KMORIKAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**11 SERIES)				
		10 OVER 30 UNDER	± ---	CHECKED BY HSHIMOYAMA	DATE 2009/07/21					
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2009/07/21	MOLEX INCORPORATED				
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-002		1 OF 2		
	B	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

F

E

D

C

B

A

F

E

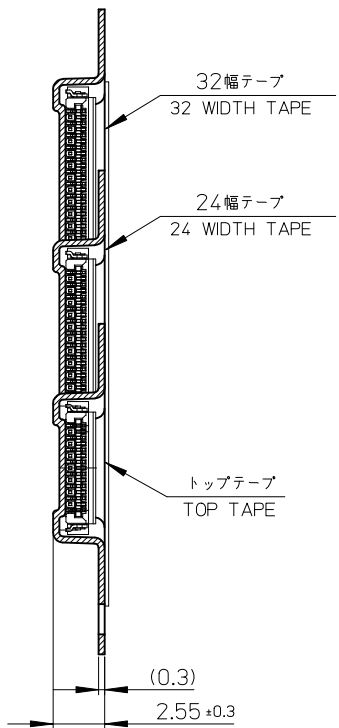
D

C

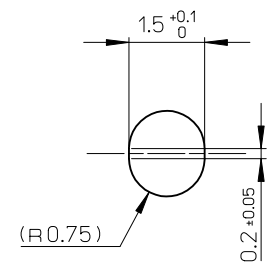
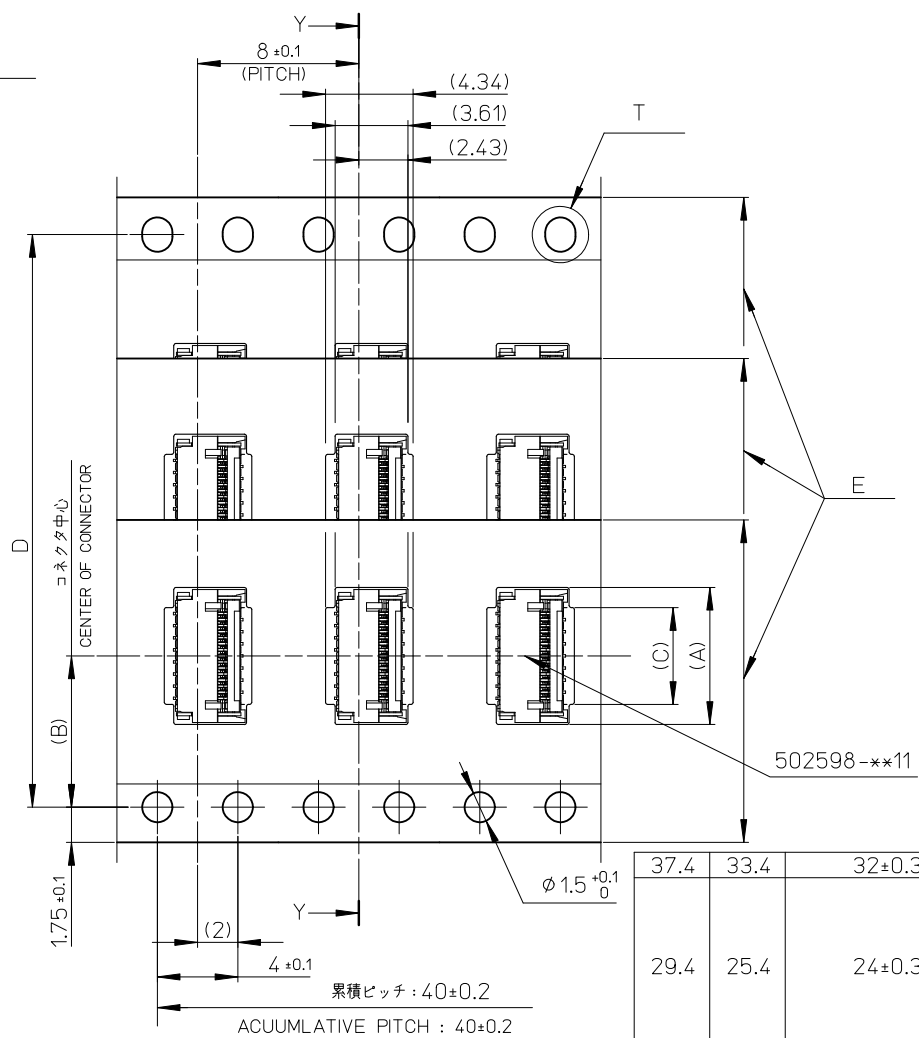
B

A

引き出し方向
PULL OUT DIRECTION



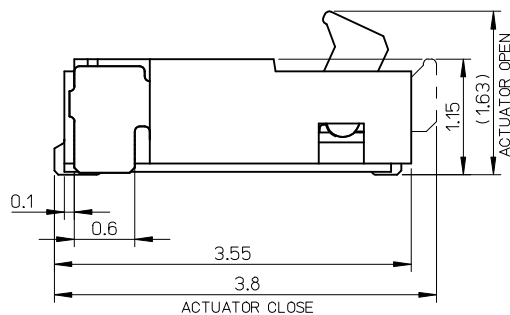
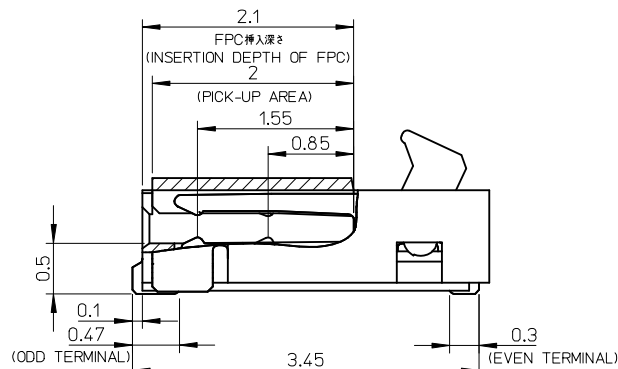
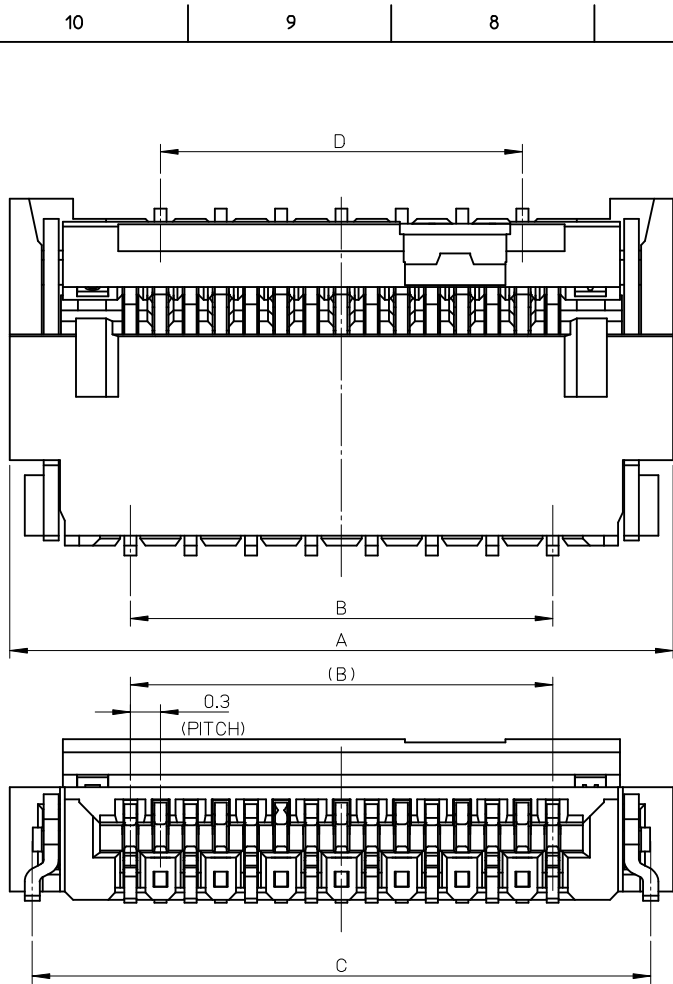
断面 Y-Y
SECTION Y-Y



T 部詳細
DETAIL T

37.4	33.4	32±0.3	28.4	15.7	14.2	17.6	502598-5191	51
29.4	25.4	24±0.3	±±	13.9	11.5	15.8	502598-4591	45
				12.1		14	502598-3991	39
				10.3		12.2	502598-3391	33
				9.1		11	502598-2991	29
				8.5		10.4	502598-2791	27
				7.9		9.8	502598-2591	25
				7.3		9.2	502598-2391	23
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2011-0028 2010/07/06 DRWN:HON001 CHKD:HSHIMOYAMA 2009/07/21 APPR:KMORIKAWA 2010/07/08	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	MATERIAL NO.		THIRD ANGLE PROJECTION		
				MM ONLY		---	METRIC					
		10 UNDER	± ---	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**11 SERIES)						
		10 OVER 30 UNDER	± ---	CHECKED BY HSHIMOYAMA	DATE 2009/07/21							
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2009/07/21	MOLEX INCORPORATED						
	ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.							
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-002				2 OF 2			
REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



注記 NOTES:

1.材質 MATERIAL

ハウジング: LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER, WHITE (NATURAL)
GLASS FILLED, UL94V-0
アクチュエータ: ポリアミド樹脂
黒色、ガラス充填、UL94HB

ACTUATOR: POLYAMIDE
BLACK GLASS FILLED, UL94HB

ターミナル: 焼青銅 (t=0.12)
TERMINAL: PHOSPHOR BRONZE (t=0.12)

金具: 焼青銅 (t=0.15)
NAIL: PHOSPHOR BRONZE (t=0.15)

2.めっき仕様 PLATING

ターミナル TERMINAL

接点部: 金めっき 0.1μm以上
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM

半田付け部: 金めっき
SOLDER TAIL AREA: GOLD

下地めっき: ニッケル 1.0μm以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

金具 NAIL
錫めっき 1.0μm以上
TIN PLATING 1.0 MICROMETER MINIMUM

下地めっき: ニッケル 1.0μm以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.

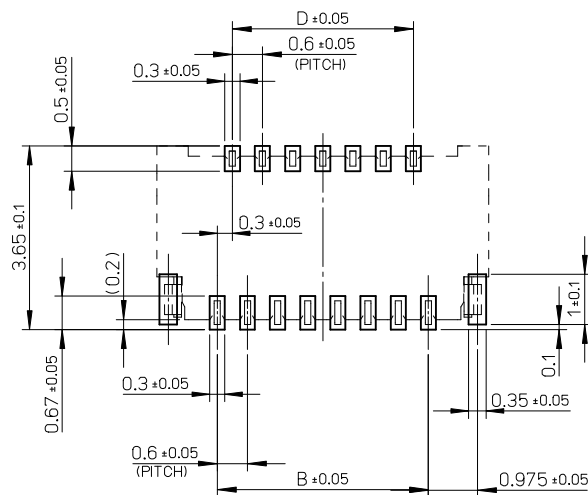
4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

5.本製品は502598-**-91の端子材料変更品である。
THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL
FOR 502598-**-91.

0.125	14.4	16.95	15	17.4	502598-5193	51
0.112	12.6	15.15	13.2	15.6	502598-4593	45
0.105	11.4	13.95	12.0	14.4	502598-4193	41
0.098	10.8	13.35	11.4	13.8	502598-3993	39
0.085	9	11.55	9.6	12	502598-3393	33
0.077	7.8	10.35	8.4	10.8	502598-2993	29
0.072	7.2	9.75	7.8	10.2	502598-2793	27
0.068	6.6	9.15	7.2	9.6	502598-2593	25
0.063	6	8.55	6.6	9	502598-2393	23
0.048	4.2	6.75	4.8	7.2	502598-1793	17
0.043	3.6	6.15	4.2	6.6	502598-1593	15
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

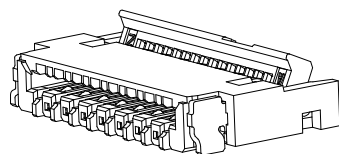
CONNECTOR SERIES NO. 502598-**-21

REVISED EC NO: J2014-0146 DRAWN:KAGUMO CHKD:K TAKAHASHI APPR:YNOGAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
		10 UNDER	± 0.2	KMIYAHARA	2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY						
		10 OVER 30 UNDER	± 0.25	KTAKAHASHI	2012/07/18							
		30 OVER	± 0.3	KMORIKAWA	2012/08/01	molex						
		ANGULAR ±1 °		MATERIAL NO.						DOCUMENT NO.		SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE						SD-502598-003		1 OF 2
REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

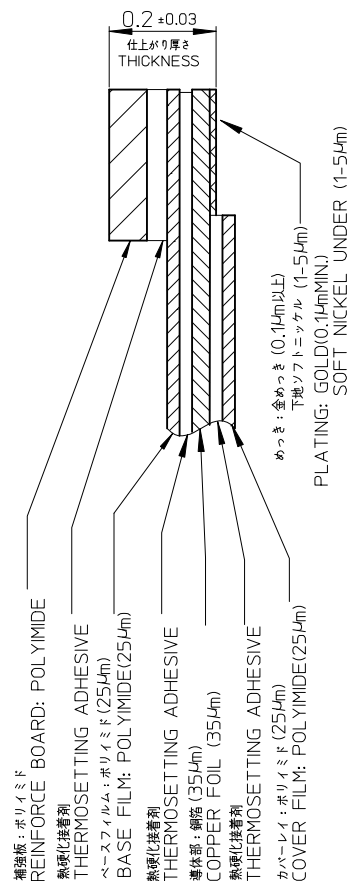


RECOMMENDED P.W.B. PATTERN LAYOUT

マスク厚: 100 μm
 マスク開口率: 100%
 SCREEN THICKNESS: 100 μm
 SCREEN OPEN RATIO: 100%

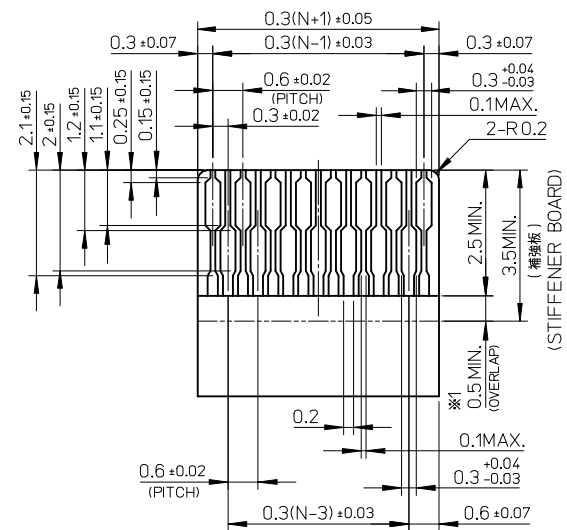


ISO VIEW (参考)



FPC構成推奨仕様

STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:

抜き方向は、導体側から補強板側を推奨致します。

補強フィルム材質は、ポリイミドを推奨致します。

接着剤は熱硬化接着剤を推奨致します。

尚、接着剤の接点部への付着は導通不良の原因になりますので、

染み出しが無い様、お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:

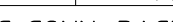
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.

RECOMMENDED MATERIAL:

STIFFENER FILM : POLYIMIDE

BONDING AGENT : THERMOSETTING AGENT

PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2014-0146 DRAWN: KAGUMO CHK'D: K TAKAHASHI APP'R: YNOGAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY			
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2012/07/18				
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2012/08/01				
		ANGULAR ±1 °		MATERIAL NO.					
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE		SD-502598-003		2 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9